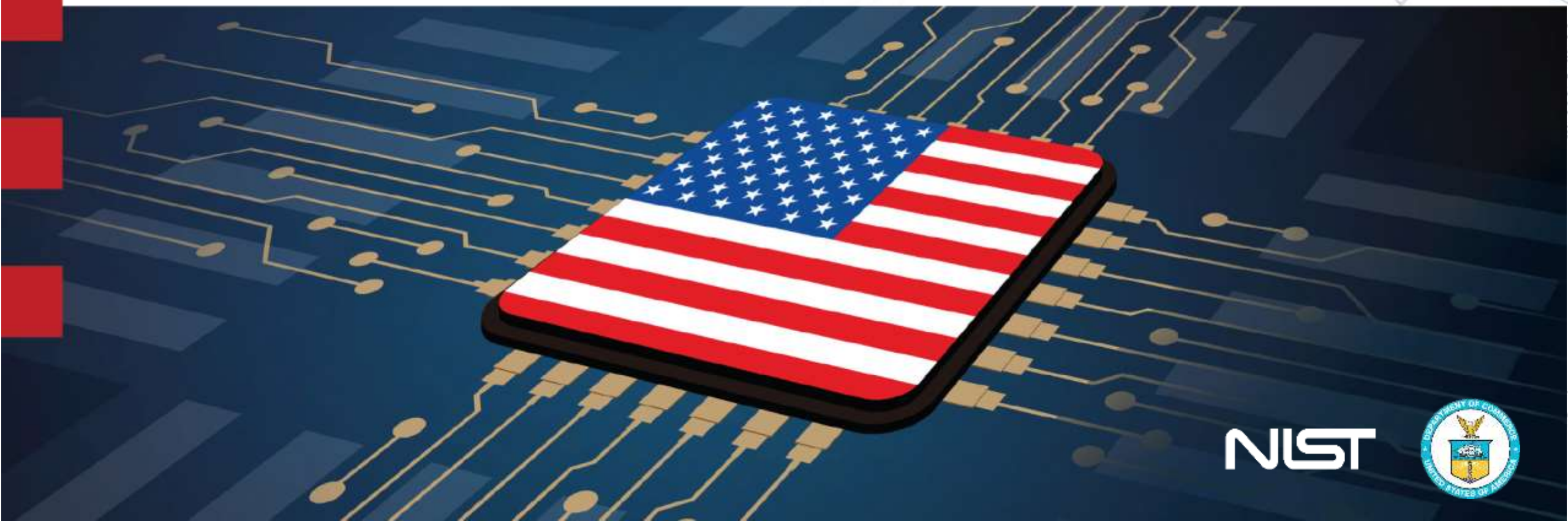
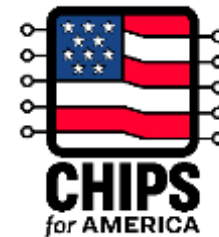


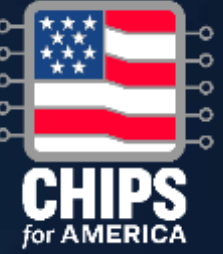
CHIPS for America Program Briefing

Presented by Robinson Pino, CHIPS Program Office
December 2022

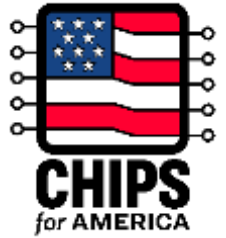


NIST



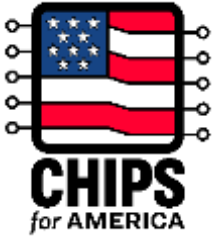


CHIPS for America Vision



Chips are the foundation of the modern world

Chips were invented in America



But most chips are made outside of the U.S.

Logic chip production by country, 2021



Memory chip production by country, 2021



One Hundred Seventeenth Congress
of the
United States of America

AT THE SECOND SESSION

*Begun and held at the City of Washington on Monday,
the third day of January, two thousand and twenty-two*

An Act

Making appropriations for Legislative Branch for the fiscal year ending September 30, 2022, and for other purposes.

*Be it enacted by the Senate and House of Representatives of
the United States of America in Congress assembled,*

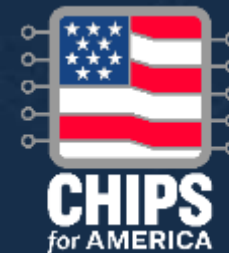
SECTION 1. TABLE OF CONTENTS.

The table of contents for this Act is as follows:

- Sec. 1. Table of contents.
- Sec. 2. References.

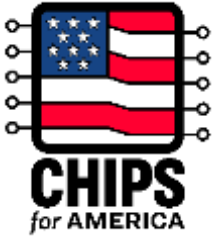
DIVISION A—CHIPS ACT OF 2022

- Sec. 101. Short title.
- Sec. 102. Creating helpful incentives to produce semiconductors (CHIPS) for America fund.
- Sec. 103. Semiconductor incentives.
- Sec. 104. Opportunity and inclusion.
- Sec. 105. Additional GAO reporting requirements.
- Sec. 106. Appropriations for wireless supply chain innovation.
- Sec. 107. Advanced manufacturing investment credit.



The CHIPS and
Science Act
of 2022

CHIPS for America Vision



Economic Security

This act enables us to build more resilient supply chains for important components.



National Security

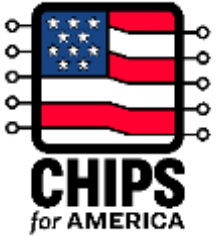
This act enables us to bring the most sophisticated technologies back to the U.S.



Future Innovation

Chips are key to the technologies and industries of the future, so we need to be at the forefront. This act will ensure long-term U.S. leadership in the sector.

CHIPS for America Incentives



\$39 billion for manufacturing

Two component programs:

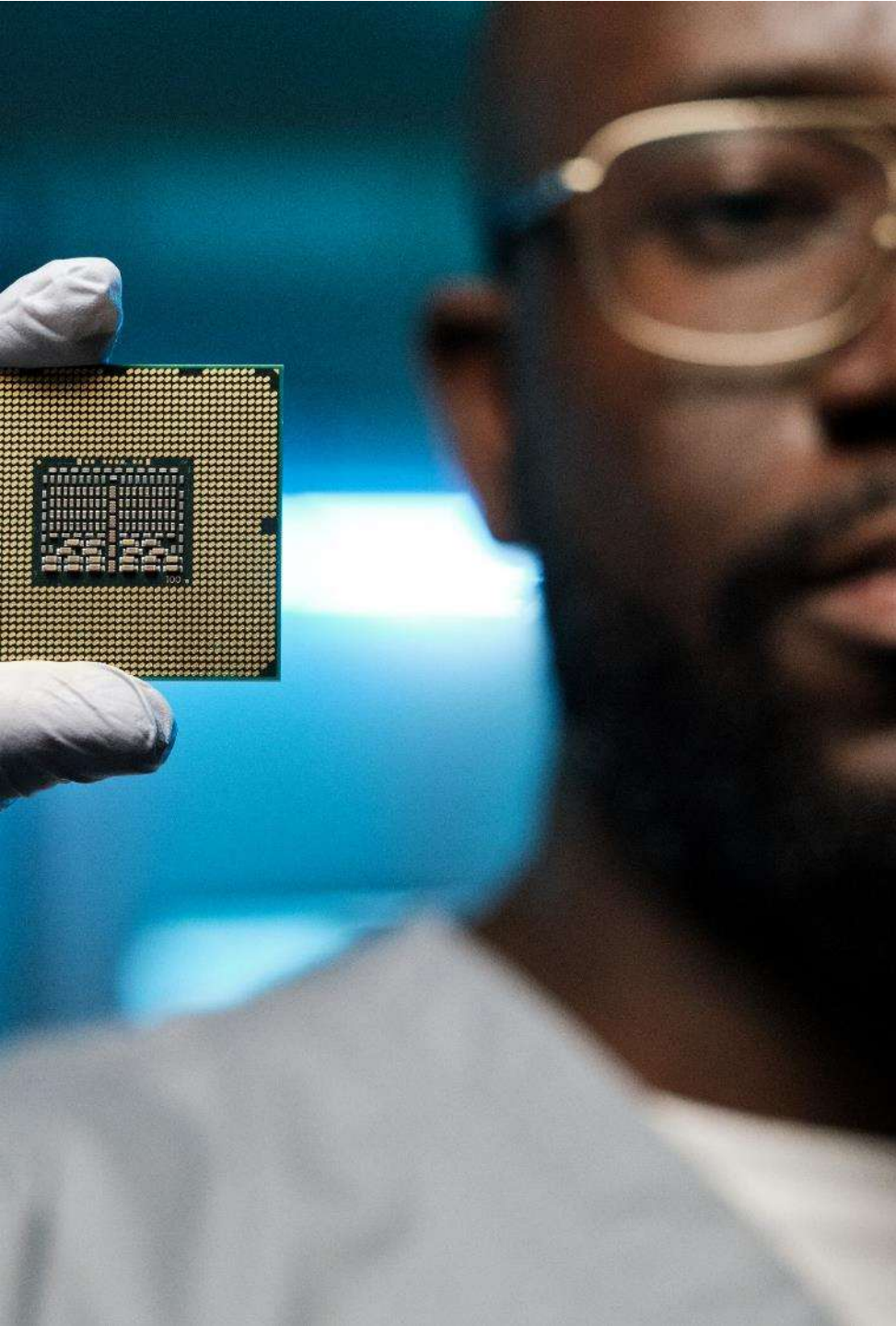
1. Attract large-scale investments in advanced technologies such as leading-edge logic and memory
2. Incentivize expansion of manufacturing capacity for mature and other types of semiconductors

\$11 billion for R&D

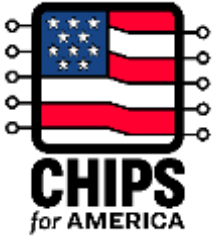
- National Semiconductor Technology Center
- National Advanced Packaging Manufacturing Program
- Manufacturing USA institute(s)
- National Institute of Standards and Technology measurement science

Together with CHIPS initiatives from other agencies, including DOD, State, NSF, and Treasury

Workforce development



Manufacturing incentives will generate:



Large-scale investments in
leading-edge logic and memory
manufacturing clusters

Manufacturing capacity for

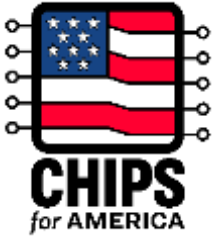
- Mature and current-gen chips
- New and specialty technologies
- Suppliers to the industry

R&D funding will create:

A national focus on transformative innovations in semiconductor technology

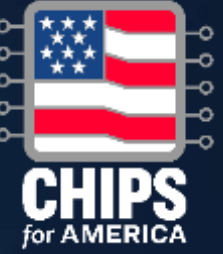
A domestic infrastructure for research and prototyping innovations

Workforce development and training



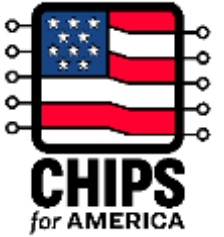
Guiding Principles

- 1 Meet economic and national security needs
- 2 Ensure long-term leadership in the sector
- 3 Strengthen and expand regional clusters
- 4 Catalyze private sector investment
- 5 Generate benefits for a range of stakeholders and communities
- 6 Protect taxpayer dollars



CHIPS for America Research and Development

R&D Ecosystem Gaps



Facilities and
equipment

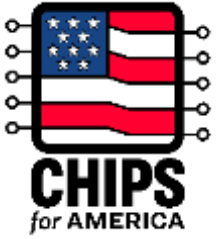
Advanced
packaging and
testing

Metrology and
characterization

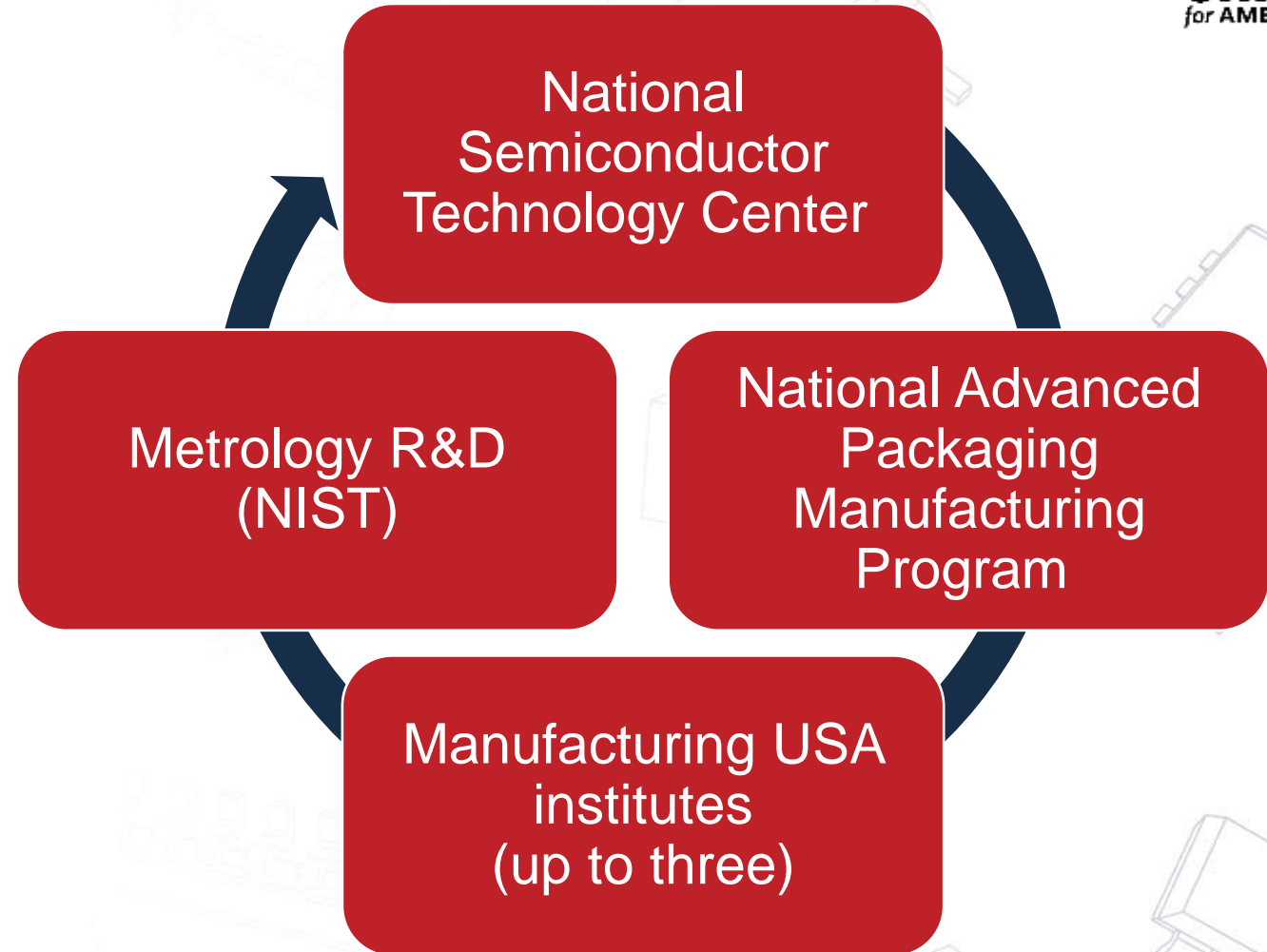
Advanced
manufacturing

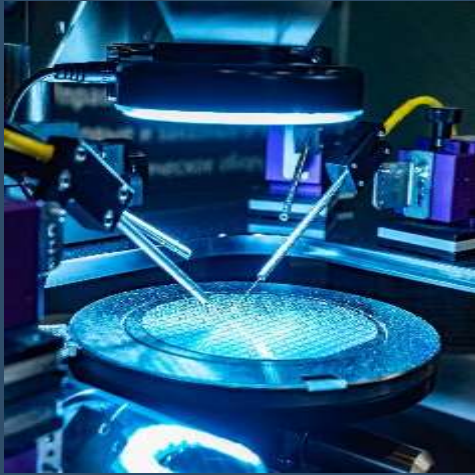
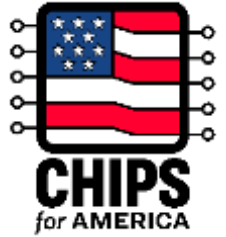
Workforce
development

Research & Development



- To strengthen and advance U.S. leadership in R&D
- An integrated ecosystem that drives innovation
- In partnership with industry, academia, government, and allies
- Informed by the Industrial Advisory Committee

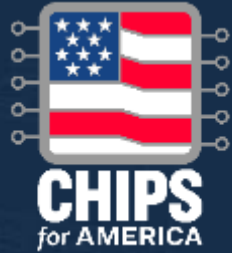




NATIONAL SEMICONDUCTOR TECHNOLOGY CENTER

MISSION

Will serve as the focal point for research and engineering throughout the semiconductor ecosystem, advancing and enabling disruptive innovation to provide U.S. leadership in the industries of the future.



NSTC MISSION ELEMENTS

Focal Point

Research and
Engineering

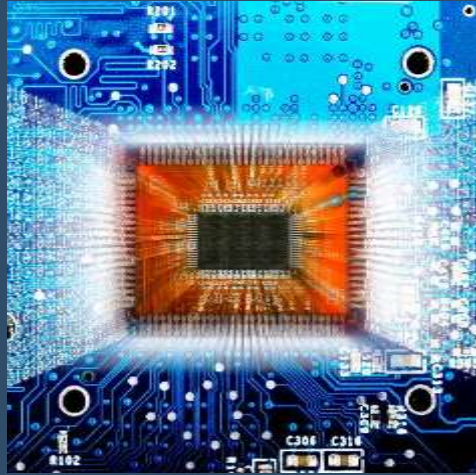
Semiconductor
Ecosystem

Advancing and
Enabling

Disruptive
Innovation

U.S.
Leadership

Industries of
the Future



NATIONAL ADVANCED PACKAGING MANUFACTURING PROGRAM

- To expand and grow U.S. capacity in advanced packaging
- Capture available market share in packaging revenue
- Pilot facility for testing and integration of new processes
- A network of public private partnerships with universities, industry, and other government agencies focused on a range of issues including:
 - Substrate technology
 - Heterogeneous integration
 - Wafer and panel-based approaches
 - Tooling and automation



NIST METROLOGY R&D

- Measurement science for new materials and packaging
- Physical metrology for next-generation microelectronics
- Computation and data
- Virtualization and automation
- Reference materials and data, and calibrations
- Standards for processes, cybersecurity, and test methods



[https://nvlpubs.nist.gov/nistpubs/
CHIPS/NIST.CHIPS.1000.pdf](https://nvlpubs.nist.gov/nistpubs/CHIPS/NIST.CHIPS.1000.pdf)

MANUFACTURING USA INSTITUTE(S)

- At least one new public-private partner institute in the Manufacturing USA network
- To advance research and commercialization of semiconductor manufacturing technologies
- Pre-competitive collaboration among researchers and manufacturers
- Virtualization, simulation, and automation
- Workforce training

Request for Information (RFI)

NIST



Published October 13, 2022

Comments close on December 12, 2022



FEDERAL REGISTER
The Daily Journal of the United States Government



N Notice

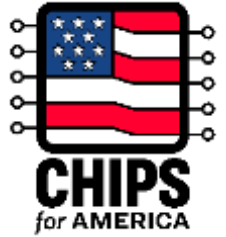
Manufacturing USA Semiconductor Institutes

A Notice by the National Institute of Standards and Technology on 10/13/2022



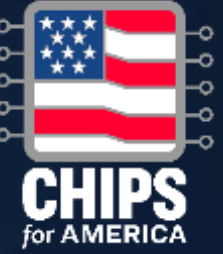
<https://www.federalregister.gov/documents/2022/10/13/2022-22221/manufacturing-usa-semiconductor-institutes>





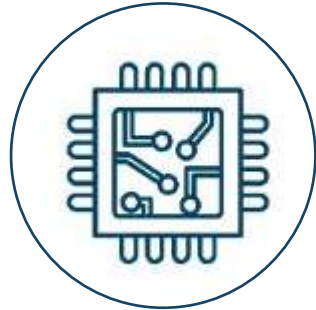
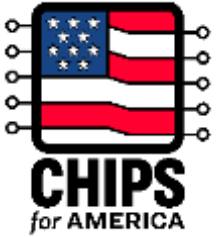
Stay Engaged

- R&D next steps
 - NSTC White Paper expected no sooner than February 2023 (6 months from enactment)
 - Additional steps to be shared after that
- Learn more
 - Visit [CHIPS.gov](https://www.chips.gov)
 - Read the Implementation Strategy
 - Join our mailing list



CHIPS for America Incentives Program

CHIPS for America will:



Return leading-edge chip manufacturing to U.S.



Expand capacity to make current/mature chips and critical supplies



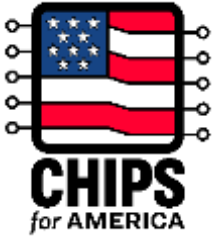
Reinforce U.S. strengths in chip design and equipment



Grow a U.S. workforce and strengthen communities

Create a domestic semiconductor ecosystem for national and economic security

Eligibility Criteria



For organizations
that are...

- private
- non-profit
- consortia

that can
substantially...

- finance
- construct
- expand
- modernize

a U.S. facility for...

- fabrication
- assembly
- testing
- packaging
- production
- R&D

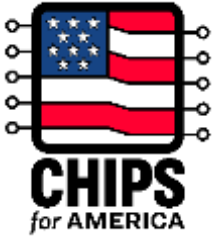
of...

- semiconductors
- materials
- manufacturing
equipment

**More details will be released in the funding application document*

Guidance for Incentive Applicants

HOW DO YOU GET STARTED?



Increase scale
and attract
private capital

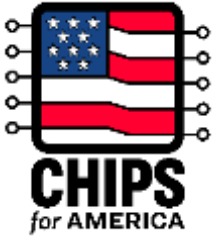
Leverage
collaborations to
build out
ecosystems

Secure additional
incentives and
support to build
clusters

Establish a
secure and
resilient supply
chain

Expand the
workforce
pipeline

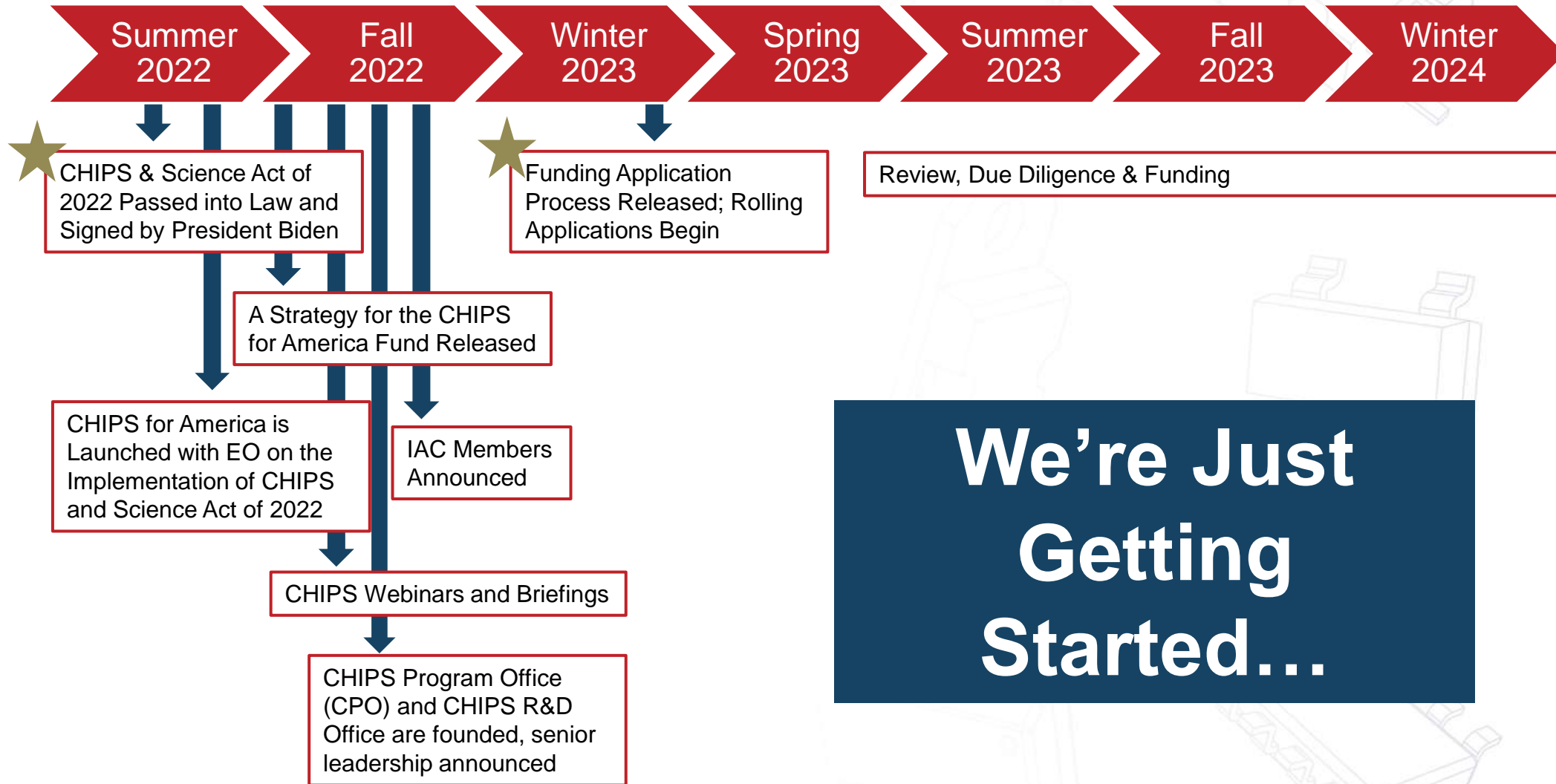
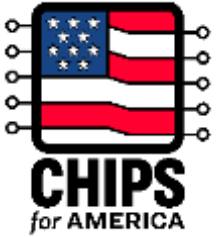
Create inclusive
opportunities for
businesses and
communities



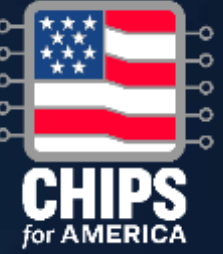
Next Steps

- Funding Application Process
 - Will be announced in February 2023 (6 months from enactment)
 - Proposals considered on a rolling basis
- Learn more
 - Visit [CHIPS.gov](https://www.chips.gov)
 - Read the Implementation Strategy, *A Strategy for the CHIPS for America Fund*
 - Join our mailing list

Timeline



*Timeline is tentative



Thank you